

微型磁珠

Ferrite Bead (Tiny Multilayer)



特性

Characteristics

非常适合EMI解决方案的小型化

Perfect for miniaturization of EMI solutions

宽阻抗范围从10到1500Ω

Wide impedance range from 10 up to 1500 Ω

工作温度: -55°C至+125°C

Operating temperature: -55 °C to +125 °C

应用

Application

一般信号线和低功率线

General signal and low power lines

音频/视频/时钟线

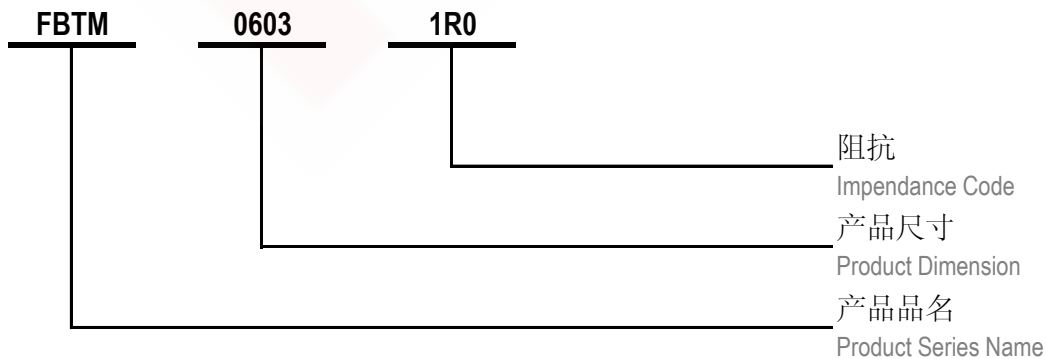
Audio/video/clock lines

小型手持设备

Small handhelds

产品品名介绍

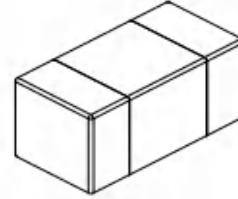
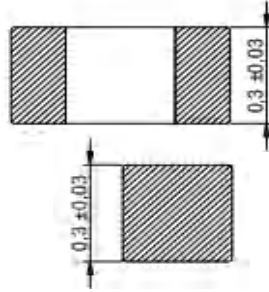
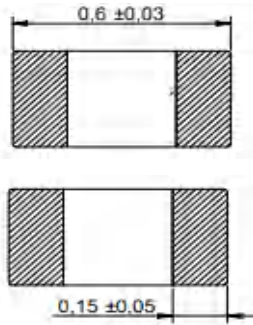
Product Number Structure





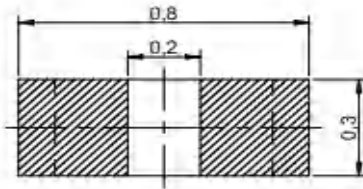
尺寸

Dimension (mm)



焊盘推荐

Land Pattern Recommended (mm)



示意图

Schematics



电性特性

Electrical Properties

型号 Part No.	阻抗 Impedance Z (Ω)	温升电流 Rated Current I _R 40°C (mA)	直流电阻 DC Resistance DCR _{max} (Ω)	卷盘数量 Taping Reel Qty. pcs
FBTM0603-100	10 ±25%	650	0.055	15,000
FBTM0603-600	60 ±25%	400	0.250	
FBTM0603-121	120 ±25%	250	0.290	
FBTM0603-241	240 ±25%	300	0.570	
FBTM0603-301	300 ±25%	400	0.610	
FBTM0603-561	560 ±25%	250	0.750	

测试状态

Test Condition

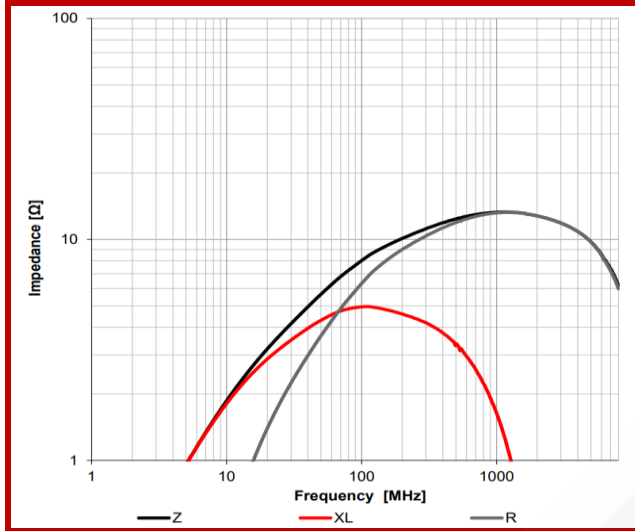
- ☆ 阻抗测试条件为 100MHz (25°C)
Impedance measure condition at 100MHz (25°C)
- ☆ 工作温度: -55°C ~ +125°C
Operating Temperature: -55°C ~ +125°C



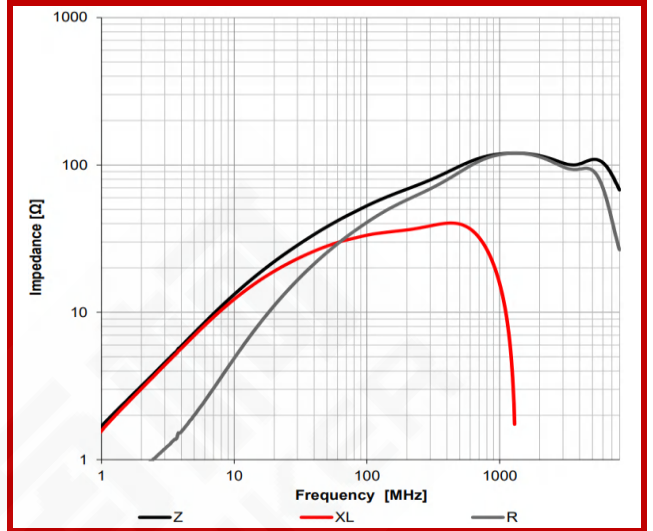
典型阻抗特性

Typical Impedance Characteristics

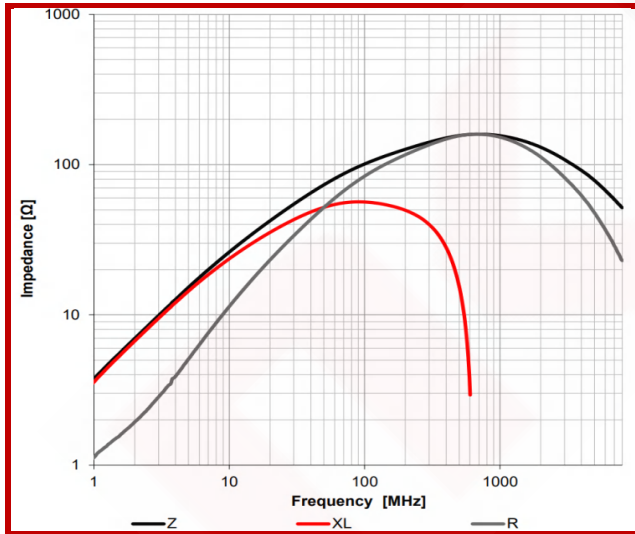
FBTM0603-100



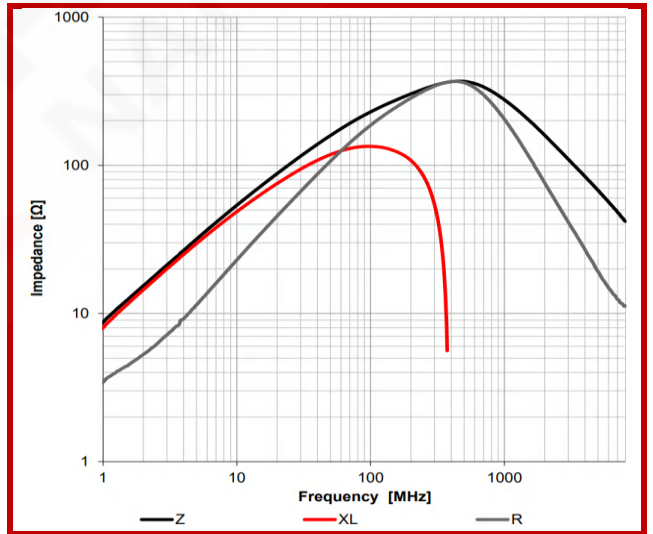
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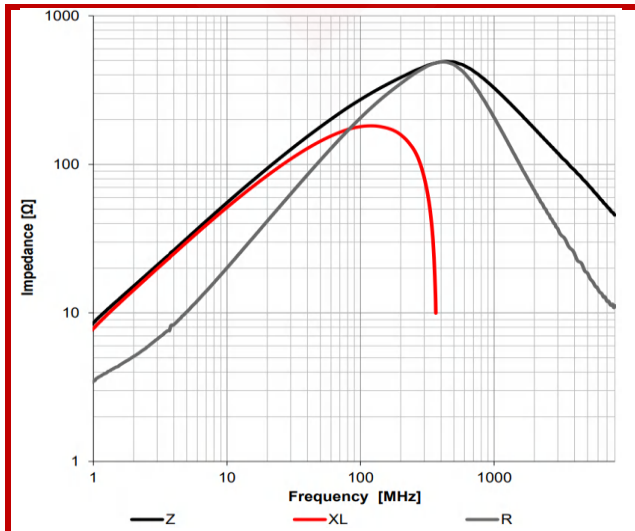
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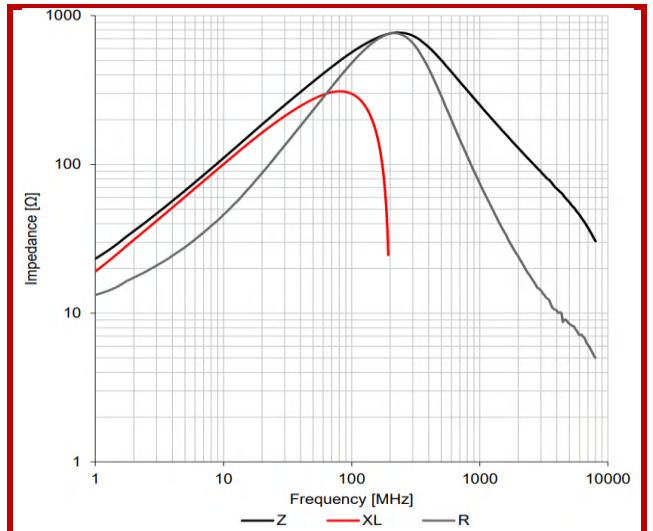
FBTM0603-241



FBTM0603-301



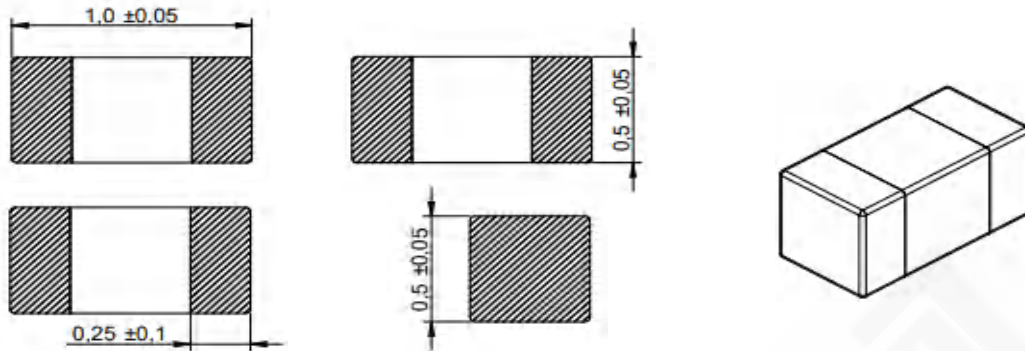
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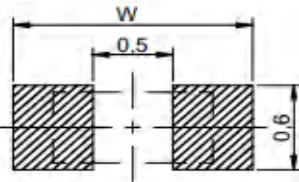
尺寸

Dimension (mm)



焊盘推荐

Land Pattern Recommended (mm)



WIDE BAND / HIGH SPEED: W = 1,5
HIGH CURRENT: W = 2,2



示意图

Schematics



电性特性

Electrical Properties

型号 Part No.	阻抗 Impedance Z (Ω)	温升电流 Rated Current I _R 40°C (mA)	直流电阻 DC Resistance DCR _{max} (Ω)	卷盘数量 Taping Reel Qty. pcs
FBTM1005-111	110 ±25%	1,200	0.070	10,000
FBTM1005-161	160 ±25%	1,000	0.120	
FBTM1005-261	260 ±25%	1,000	0.120	
FBTM1005-461	460 ±25%	500	0.350	
FBTM1005-601	600 ±25%	850	0.220	
FBTM1005-102	1,000 ±25%	480	0.430	
FBTM1005-152	1,500 ±25%	500	0.430	
FBTM1005-182	1,800 ±25%	210	1.910	

测试状态

Test Condition

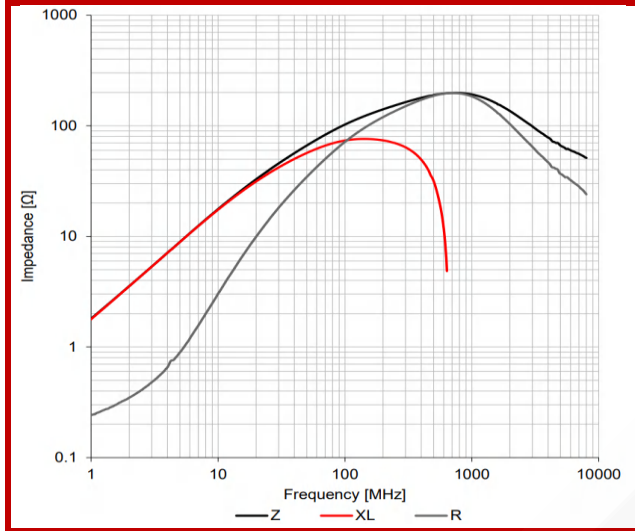
- ☆ 阻抗测试条件为 100MHz (25°C)
Impedance measure condition at 100MHz (25°C)
- ☆ 工作温度: -55°C ~ +125°C
Operating Temperature: -55°C ~ +125°C



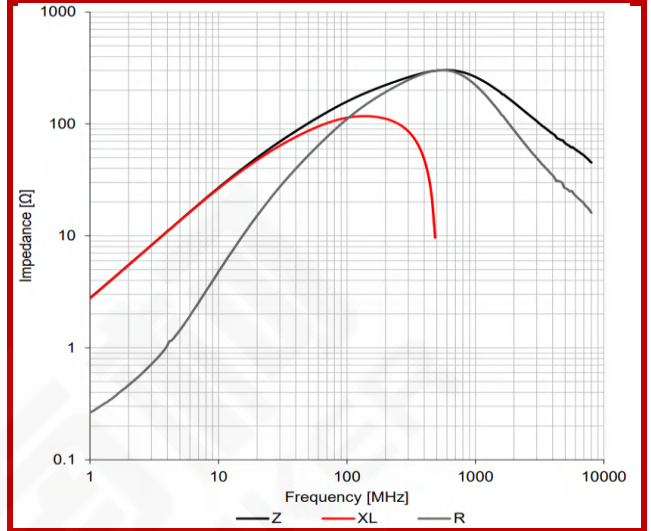
典型阻抗特性

Typical Impedance Characteristics

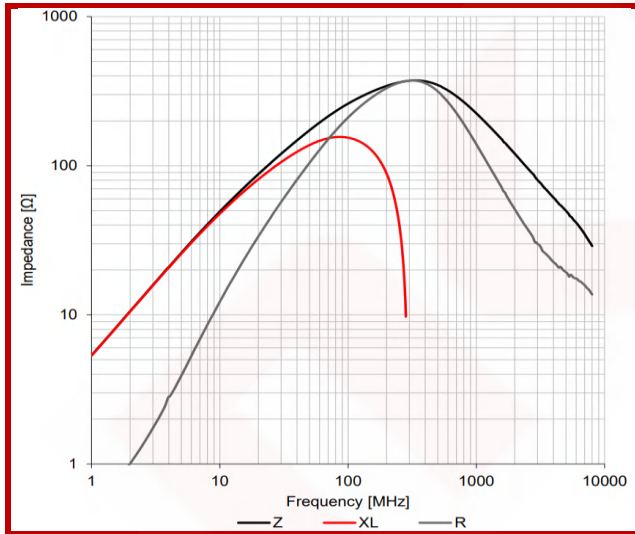
FBTM1005-111



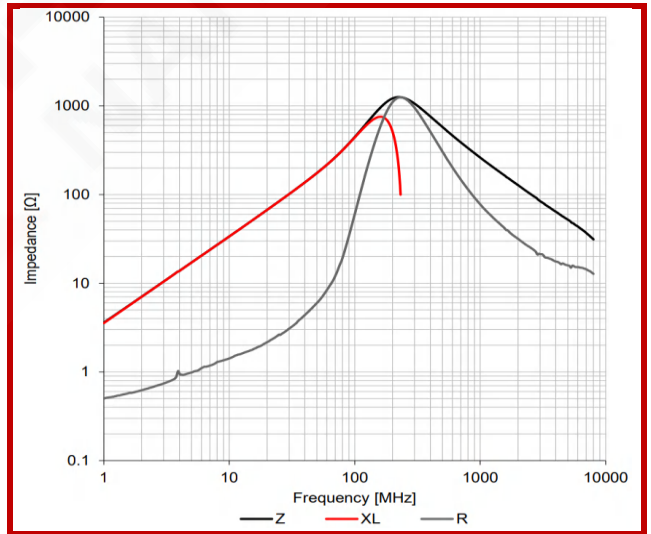
FBTM1005-161



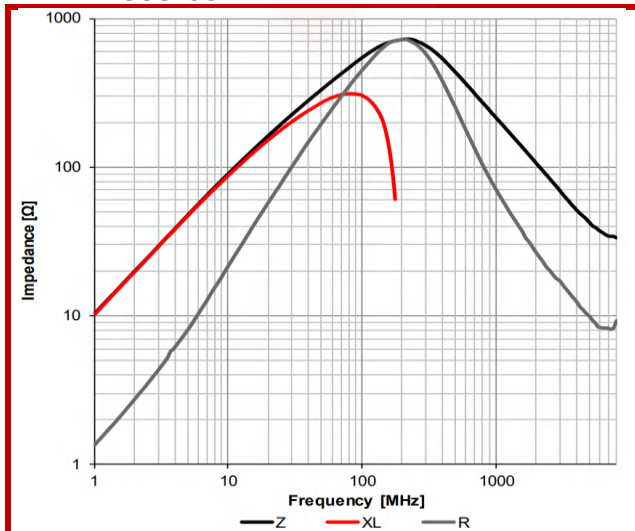
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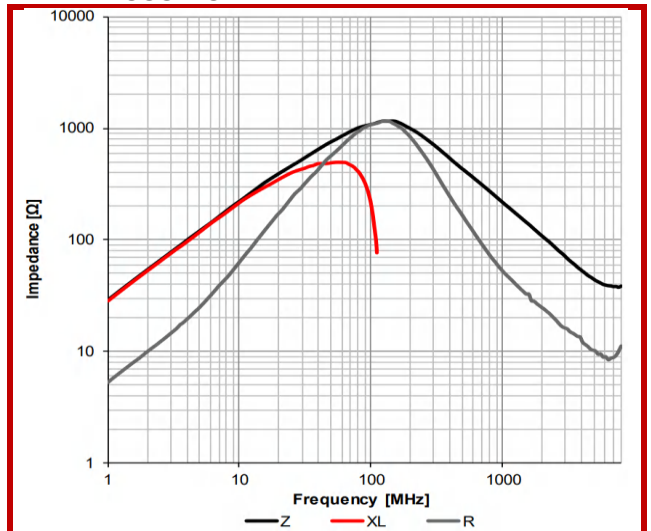
FBTM1005-461



FBTM1005-601



FBTM1005-102

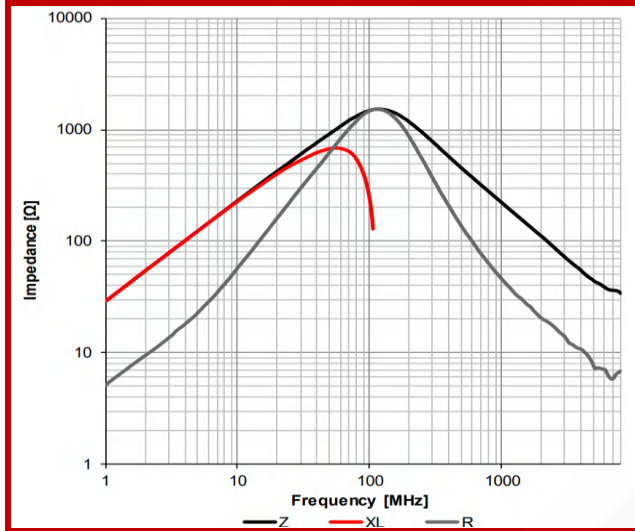




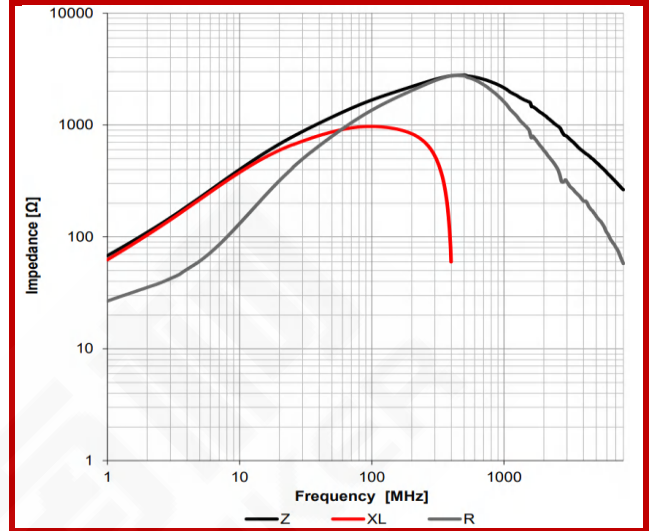
典型阻抗特性

Typical Impedance Characteristics

FBTM1005-152



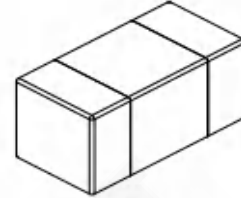
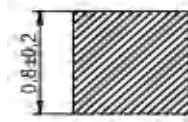
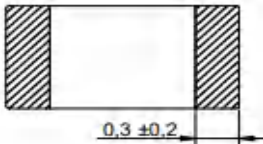
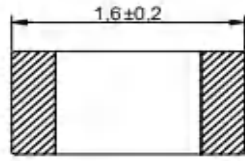
FBTM1005-182





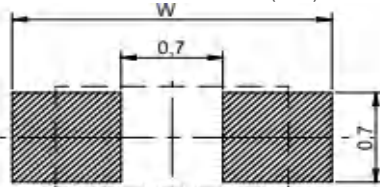
尺寸

Dimension (mm)



焊盘推荐

Land Pattern Recommended (mm)



WIDE BAND / HIGH SPEED: W = 2.2
HIGH CURRENT: W = 2.6



示意图

Schematics



电性特性

Electrical Properties

型号 Part No.	阻抗 Impedance Z (Ω)	温升电流 Rated Current I _R 40°C (mA)	直流电阻 DC Resistance DCR _{max} (Ω)	卷盘数量 Taping Reel Qty. pcs
FBTM1608-220	22 ±25%	7,500	0.003	4,000
FBTM1608-601	600 ±25%	1,500	0.090	

测试状态

Test Condition

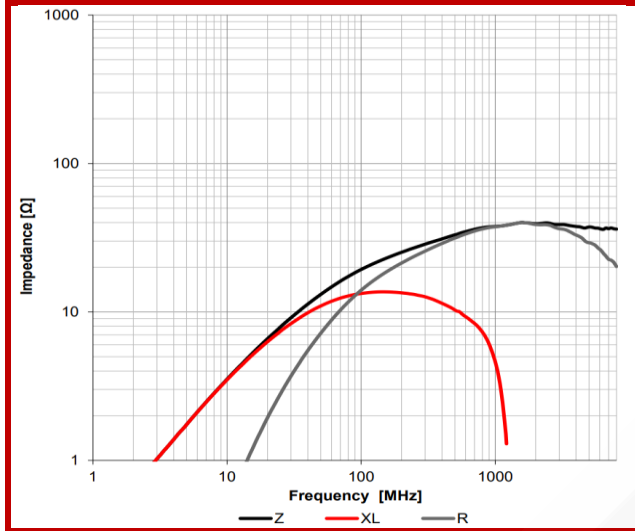
- ☆ 阻抗测试条件为 100MHz (25°C)
Impedance measure condition at 100MHz (25°C)
- ☆ 工作温度: -55°C ~ +125°C
Operating Temperature: -55°C ~ +125°C



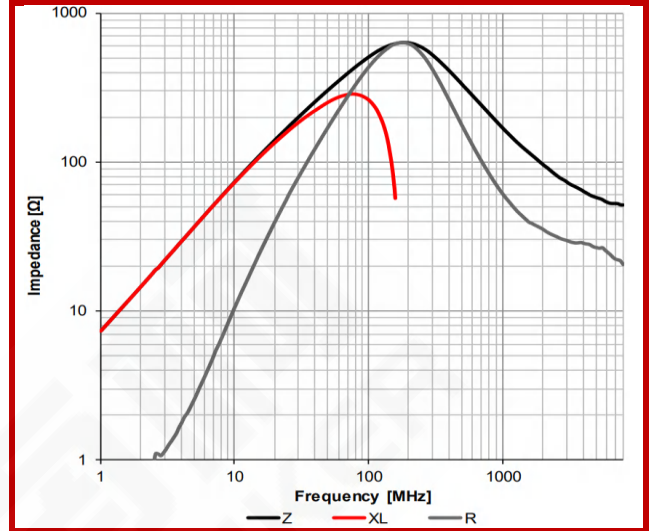
典型阻抗特性

Typical Impedance Characteristics

FBTM1608-220



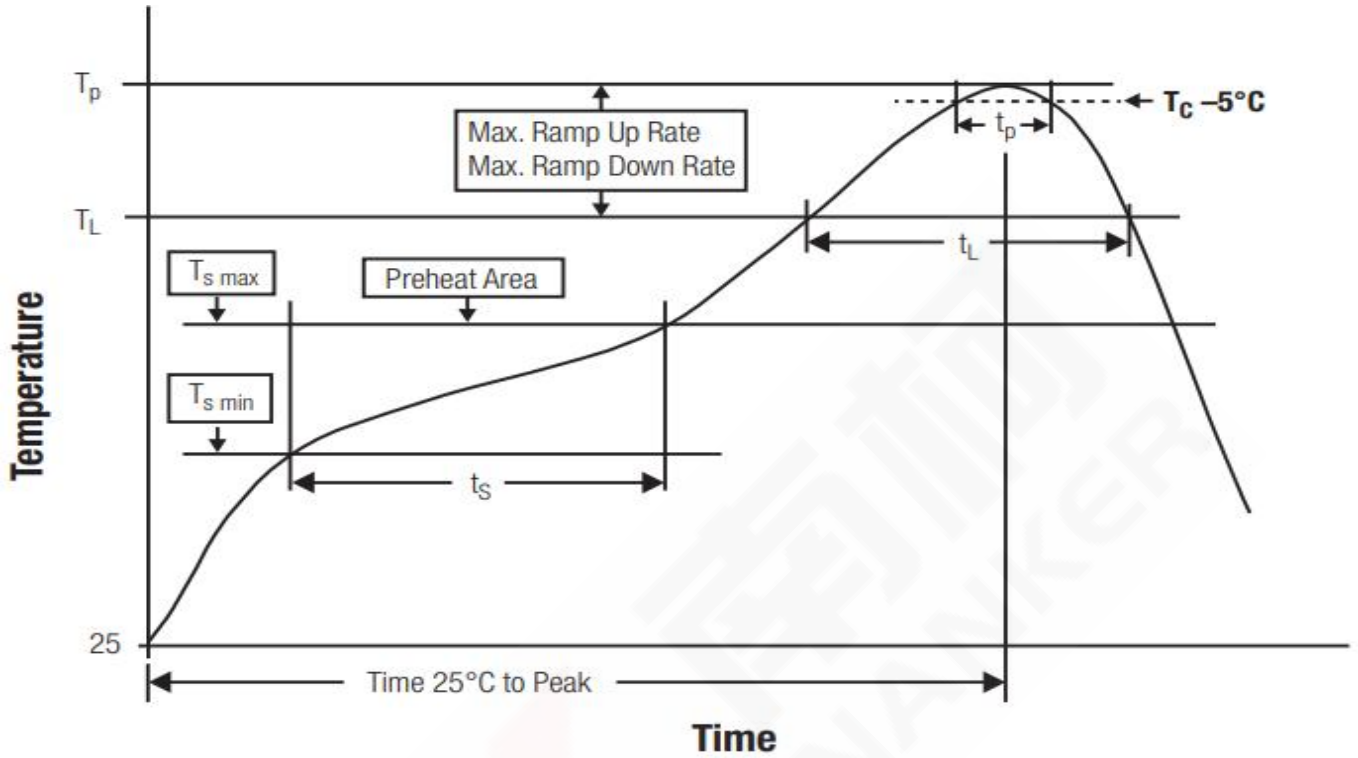
FBTM1608-601





回流焊曲线图

Classification Reflow Profile for SMT Components



封装体峰值温度(Tp)分类

Classification Reflow Soldering Profile:

	封装厚度 Package Thickness	封装体积 Package Volume		
		<350 mm ³	350~2,000 mm ³	>2,000 mm ³
无铅装配 PB-Free Assembly	<1.60mm	260°C	260°C	260°C
	1.60~2.50mm	260°C	250°C	245°C
	>2.50mm	260°C	245°C	245°C

- ◆ 回流焊参照标准 IPC/JEDEC J-STD-020D。
Reflow is refer to standard IPC/JEDEC J-STD-020D.